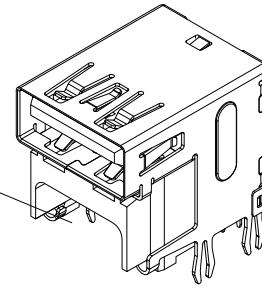
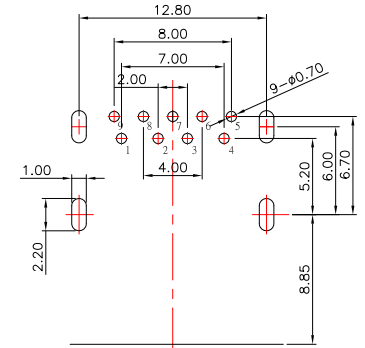


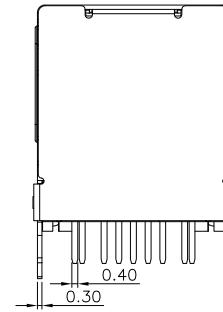
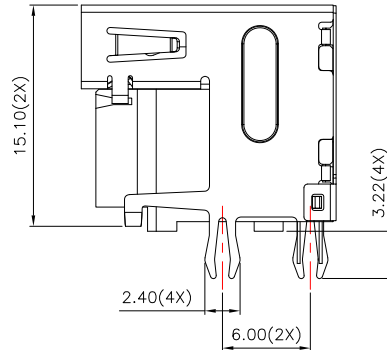
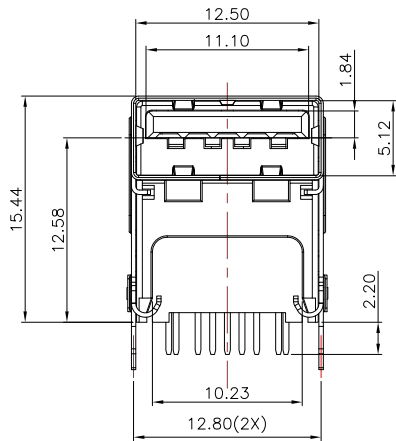
Type C 放置位置



USB 3.0 AF 架高型的下方空間是擺放Type C connector, 先打件Type C connector, 再打件USB 3.0 AF



RECOMMENDED PCB LAYOUT



NOTE:

1.MATERIAL:

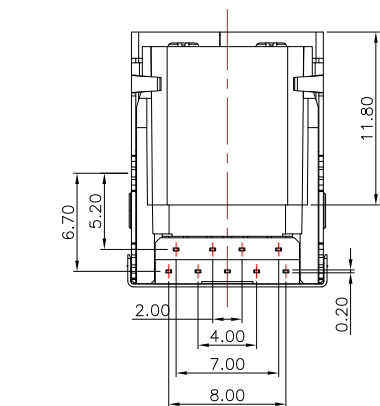
- 1.1 Housing: PA66
- 1.2 Contact: PHOSPHOR BRONZE
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Current Rate: 1.8 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -40°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N



SUA-110H13-30xx-S277

鍍層厚度: COLOR:

Blank : 1u"
2 : 15u"
3 : 30u"

BLUE : Blank
Black : B
Red : R

Contact Number	Signal Name
PIN1	VBUS
PIN2	D-
PIN3	D+
PIN4	GND
PIN5	StdA_SSRX-
PIN6	StdA_SSRX+
PIN7	GND_DRAIN
PIN8	StdA_SSTX-
PIN9	StdA_SSTX+
Shell	Shield



TOLERANCE UNLESS OTHERWISE STATED: Up to 5 ±0.2, Above 5 ~ 15 ±0.3, Above 15 ~ 30 ±0.4, Above 30 ~ 50 ±0.5, Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY: Jack Lu	DATE: 11/26/21	MAT'L	TITLE: CONNECTOR
CHECKED BY: Jacky Chen	DATE: 11/26/21	FINISH	MODLE: USB AF DIP 架高 CH=12.58mm
APPROVED BY: Tony Kao	DATE: 11/26/21	SCALE: 1 : 1	DWG NO. SUA-110H13-30xx-S277
		SHEET NO. 1 of 1	PART NO. SUA-110H13-30xx-S277
			SIZE: A4
			VER: R1

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	新增產品說明和更新材質	Jack	112621